BU2523AF

GENERAL DESCRIPTION

New generation, high-voltage, high-speed switching npn transistor in a plastic full-pack envelope intended for use in horizontal deflection circuits of HDTV receivers and pc monitors.

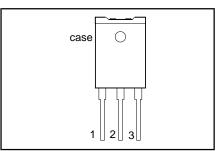
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CESM}	Collector-emitter voltage peak value	$V_{BF} = 0 \text{ V}$	-	1500	V
V _{CEO}	Collector-emitter voltage (open base)		-	800	V
I _C	Collector current (DC)		-	11	Α
1 1	Collector current peak value		-	29	Α
P _{tot}	Total power dissipation	T _{hs} ≤ 25 °C	-	45	W
V _{CEsat}	Collector-emitter saturation voltage	$I_{\rm C} = 5.5 \text{A}; I_{\rm B} = 1.1 \text{A}$	-	5.0	V
Csat	Collector saturation current	f = 64 kHz	5.5	-	Α
l t _f	Fall time	$I_{Csat} = 5.5 \text{ A}$; $f = 64 \text{ kHz}$	0.15	0.3	μs

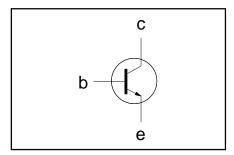
PINNING - SOT199

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	
case	isolated	

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1500	٧
V _{CEO}	Collector-emitter voltage (open base)		-	800	V
I _C	Collector current (DC)		-	11	Α
I _{CM}	Collector current peak value		-	29	Α
I _B	Base current (DC)		-	7	Α
I _{BM}	Base current peak value		-	10	Α
-I _{B(AV)}	Reverse base current	average over any 20 ms period	-	175	mA
-I _{BM}	Reverse base current peak value 1		-	7	Α
P _{tot}	Total power dissipation	$T_{hs} \leq 25 ^{\circ}C$	-	45	W
T _{stg}	Storage temperature		-55	150	°C
T _j	Junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R _{th j-hs}	Junction to heatsink	with heatsink compound	-	2.8	K/W
R _{th j-a}	Junction to ambient	in free air	35	-	K/W

¹ Turn-off current.

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. ≤ 65 % ; clean and dustfree	1		2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	22	-	pF

STATIC CHARACTERISTICS

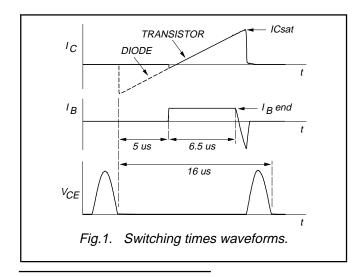
T_{hs} = 25 °C unless otherwise specified

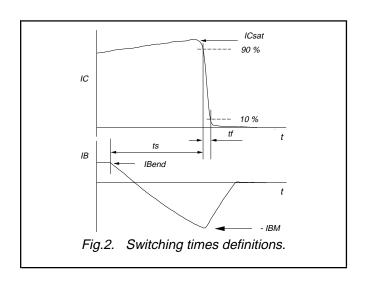
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CES}	Collector cut-off current ²	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$	-	-	1.0	mΑ
I _{CES}		$egin{array}{l} V_{BE} = 0 \ V; \ V_{CE} = V_{CESMmax} \ V_{BE} = 0 \ V; \ V_{CE} = V_{CESMmax}; \ T_i = 125 \ ^{\circ}C \end{array}$	-	-	2.0	mA
I _{EBO}	Emitter cut-off current	$V_{EB} = 7.5 \text{ V}; I_{C} = 0 \text{ A}$	-	-	1.0	mΑ
BV_{EBO}	Emitter-base breakdown voltage	$I_{R} = 1 \text{ mA}$	7.5	13.5	-	V
V _{CEOsust}	Collector-emitter sustaining voltage	$I_{B}^{F} = 0 \text{ A}; I_{C} = 100 \text{ mA};$ L = 25 mH	800	-	-	V
V_{CEsat}	Collector-emitter saturation voltage	$I_{\rm C} = 5.5 \text{A}; I_{\rm B} = 1.1 \text{A}$	-	-	5.0	V
V _{BEsat}	Base-emitter saturation voltage	$I_{C} = 5.5 \text{ A}; I_{B} = 1.1 \text{ A}$	-	-	1.0	V
h _{FE}	DC current gain	$I_{C} = 1 \text{ A}; V_{CE} = 5 \text{ V}$ $I_{C} = 5.5 \text{ A}; V_{CE} = 5 \text{ V}$	-	14	-	
h _{FE}	_	$I_{\rm C} = 5.5 \text{A}; V_{\rm CE} = 5 \text{V}$	5	8	10.3	

DYNAMIC CHARACTERISTICS

 T_{hs} = 25 $^{\circ}$ C unless otherwise specified

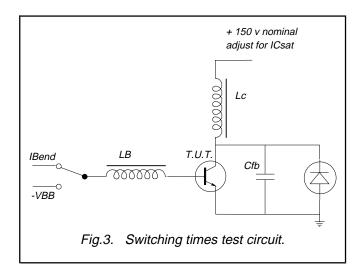
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
	Switching times (64 kHz line deflection circuit)	$ \begin{vmatrix} I_{Csat} = 5.5 \text{ A}; \ L_{C} = 200 \ \mu\text{H}; \ C_{fb} = 4 \ n\text{F}; \\ V_{CC} \ 145 \ V; \ I_{B(end)} = 0.56 \ A; \\ L_{B} = 0.4 \ \mu\text{H}; \ -V_{BB} = -4 \ V; \ -I_{BM} = 3.3 \ A \ \end{vmatrix} $			
t _s	Turn-off storage time Turn-off fall time		1.5 0.15	2.0 0.3	μs μs

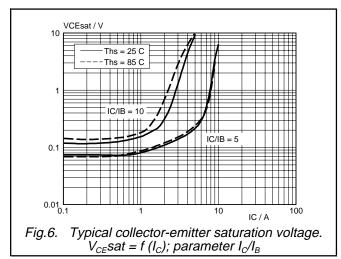


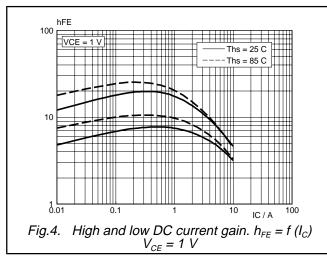


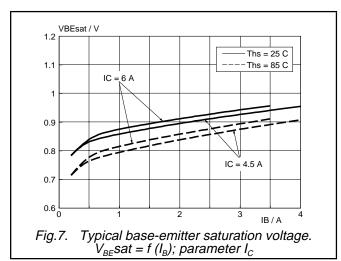
² Measured with half sine-wave voltage (curve tracer).

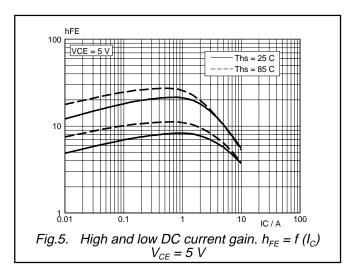
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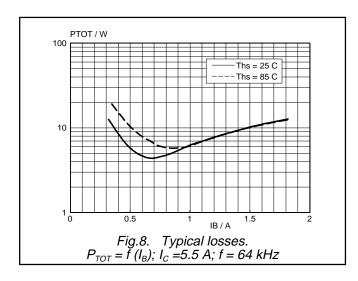








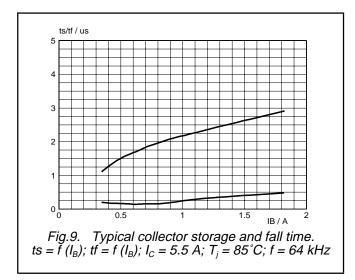


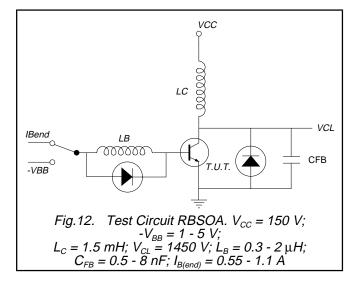


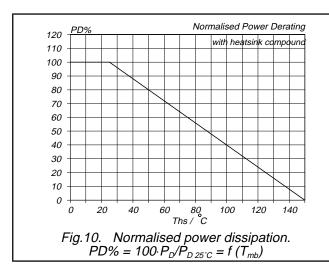
Philips Semiconductors Product specification

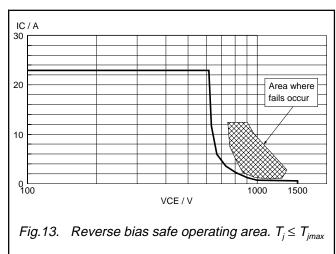
Silicon Diffused Power Transistor

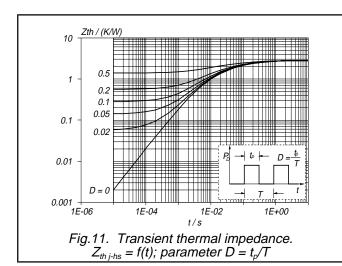
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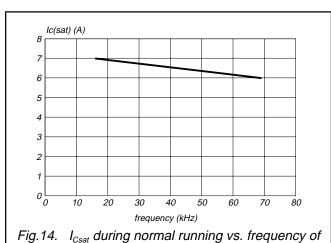
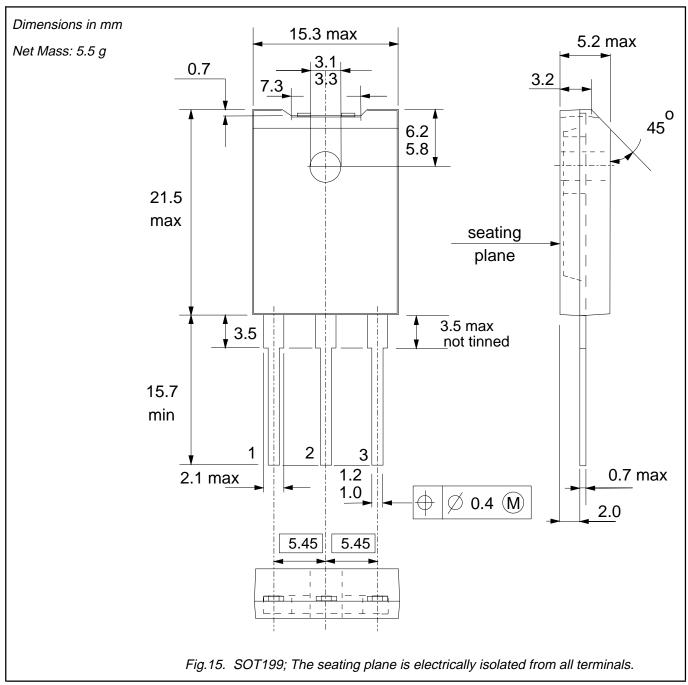


Fig.14. I_{Csat} during normal running vs. frequency of operation for optimum performance

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MECHANICAL DATA



- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Silicon Diffused Power Transistor

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DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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